

wherein said electronic element, element placement pad, part of said first lead, and a part of said second lead are sealed with a sealing resin in a package, said first lead being bent in an S shape, a bending depth d therefore being at least as large as the thickness t of said first lead, and the thickness T of said resin on a non-device side of said element placement pad being smaller than said bending depth d , and

wherein the sealing resin is injected from a position on a longer side of the package, said position being offset toward one shorter side thereof.

- a1
cont.
2. (Amended) An electronic device according to claim 1, wherein the spacing between said element placement pad and said second lead is no greater than 0.12 mm.
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- a2
4. (Amended) An electronic device according to claim 1, wherein widths of inner lead parts of said first and second leads within said sealing resin are substantially uniform.
5. (Amended) An electronic device according to claim 1, wherein the thickness of said electronic element is substantially the same as the thickness t of said first lead.
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- a3
7. (Amended) An electronic device according to claim 1, wherein a bending radius R on an outer surface of a bent part of said first lead near a bottom surface of said sealing resin is at least 0.05 mm and is no greater than the lead thickness t .
8. (Amended) An electronic device according to claim 1, wherein the sealing resin contains a filler, whose particle diameter is not greater than half the bending depth d of the said first lead.
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